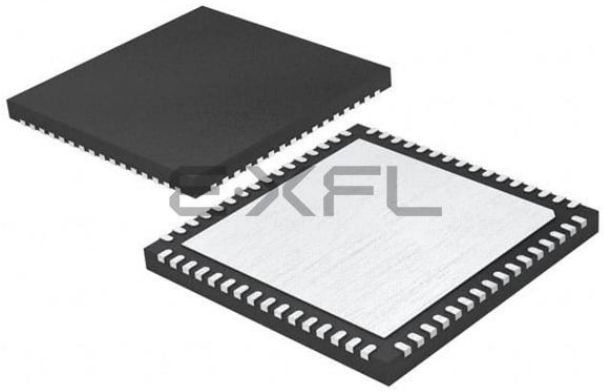
Microchip Technology - DSPIC33EP512MC506T-I/MR Datasheet



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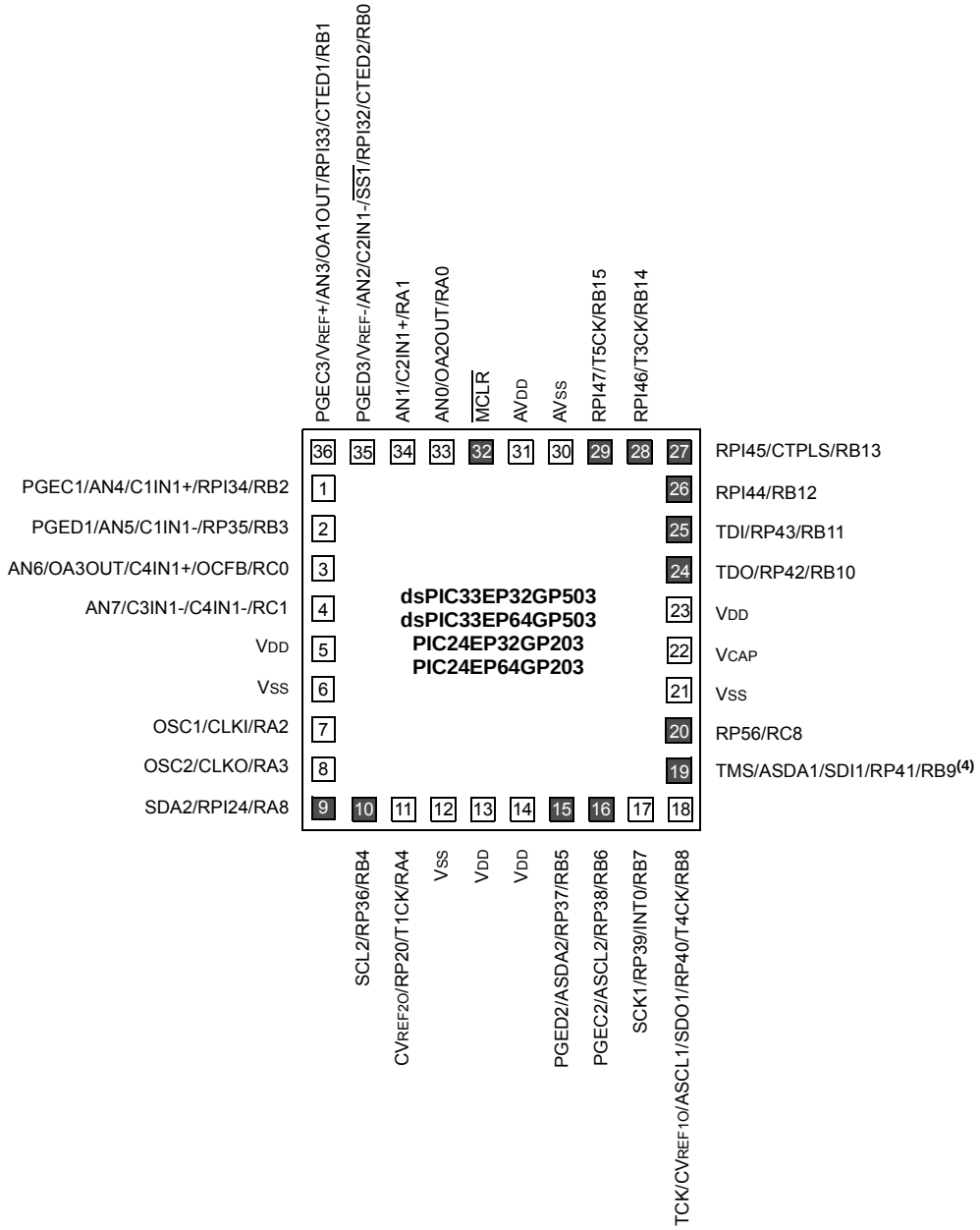
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	53
Program Memory Size	512KB (170K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	24K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 16x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-VQFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep512mc506t-i-mr

Pin Diagrams (Continued)

36-Pin VTLA(1,2,3)

■ = Pins are up to 5V tolerant



Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 "Peripheral Pin Select (PPS)"** for available peripherals and for information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

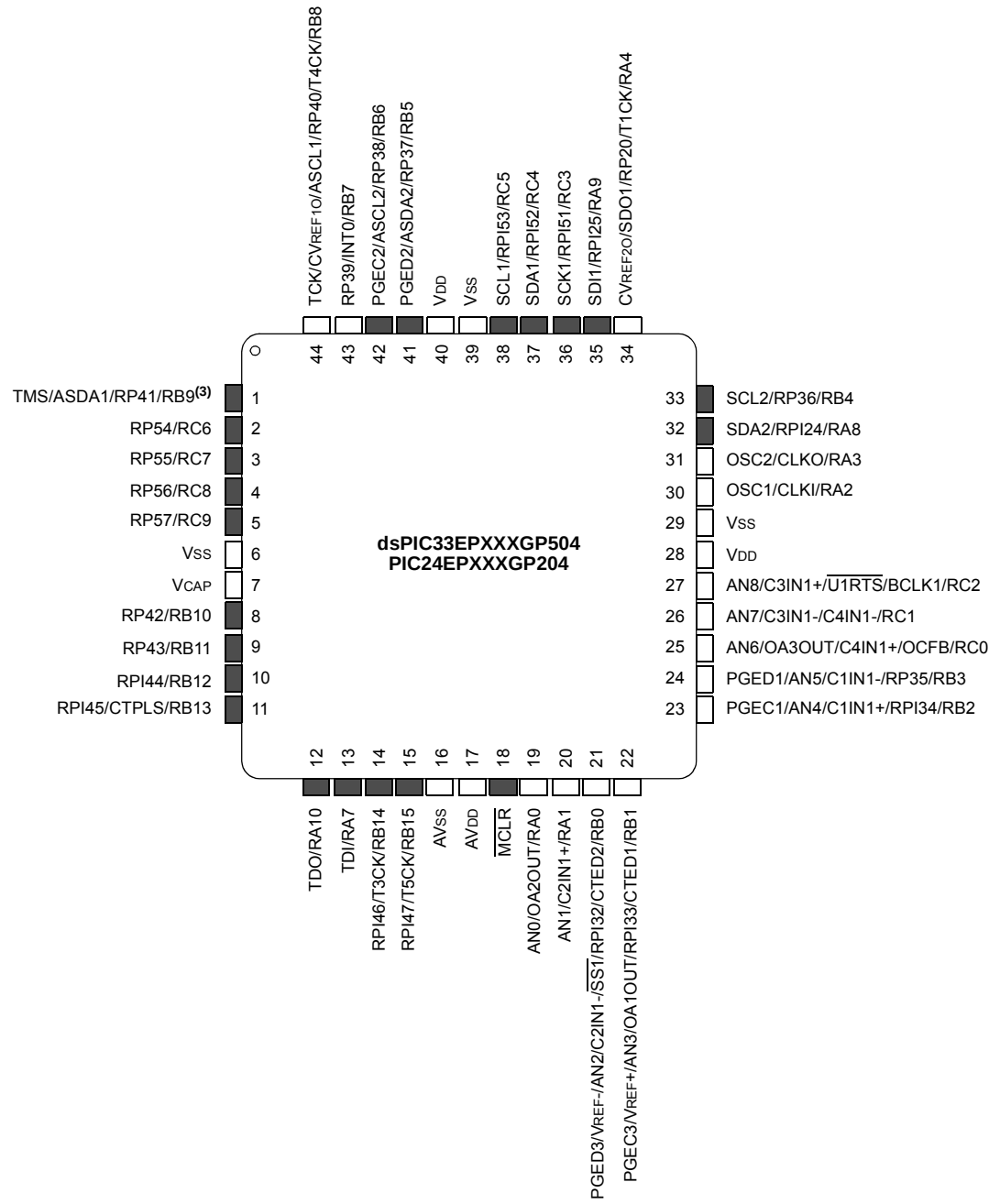
3: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

4: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

Pin Diagrams (Continued)

44-Pin TQFP(1,2)

■ = Pins are up to 5V tolerant



Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 "Peripheral Pin Select (PPS)"** for available peripherals and for information on limitations.

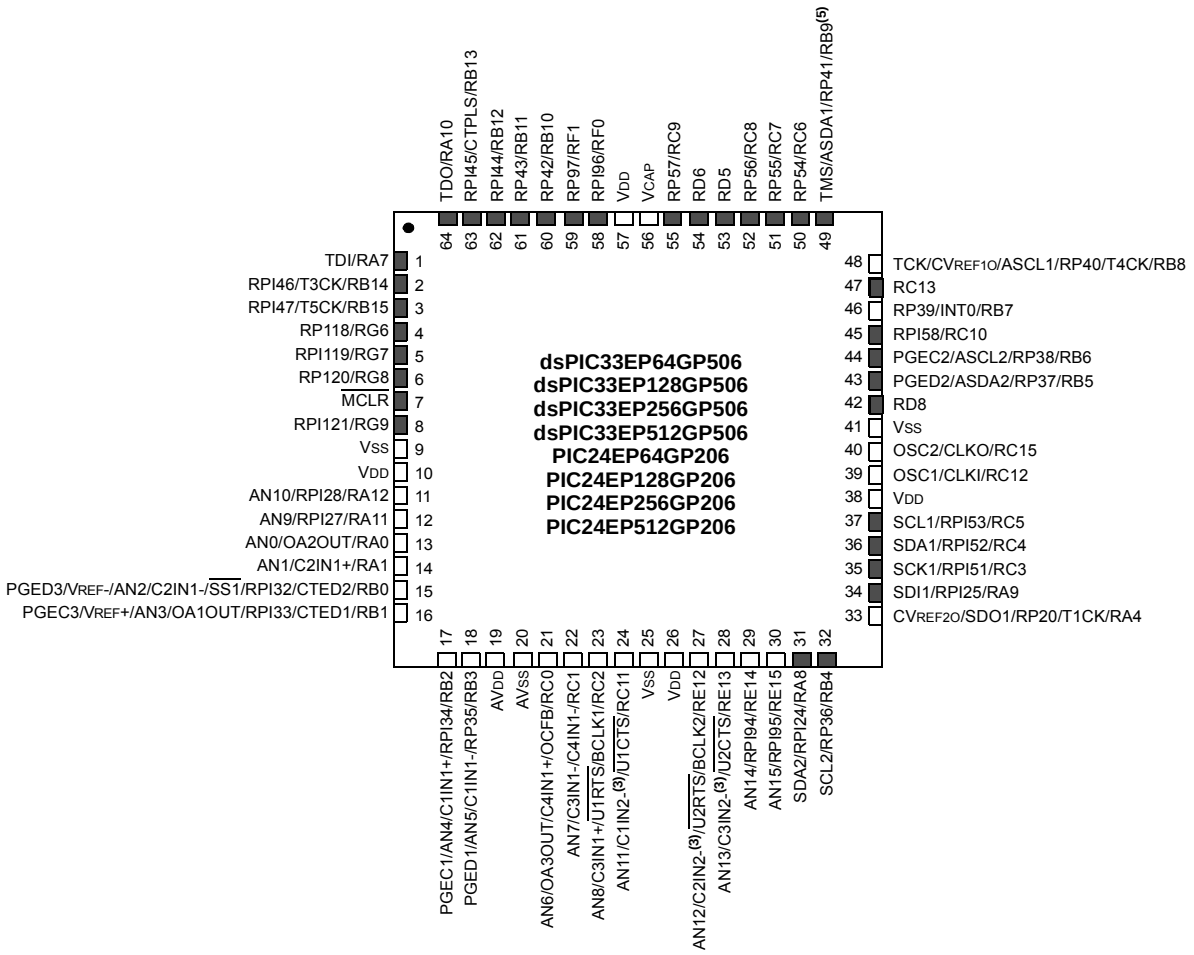
2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

3: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

Pin Diagrams (Continued)

64-Pin QFN(1,2,3,4)

■ = Pins are up to 5V tolerant



Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 "Peripheral Pin Select (PPS)"** for available peripherals and for information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

3: This pin is not available as an input when OPMODE (CMxCON<10>) = 1.

4: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

5: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

2.5 ICSP Pins

The PGECx and PGEDx pins are used for ICSP and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Pull-up resistors, series diodes, and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin Voltage Input High (V_{IH}) and Voltage Input Low (V_{IL}) requirements.

Ensure that the "Communication Channel Select" (i.e., PGECx/PGEDx pins) programmed into the device matches the physical connections for the ICSP to MPLAB® PICkit™ 3, MPLAB ICD 3, or MPLAB REAL ICE™.

For more information on MPLAB ICD 2, ICD 3 and REAL ICE connection requirements, refer to the following documents that are available on the Microchip web site.

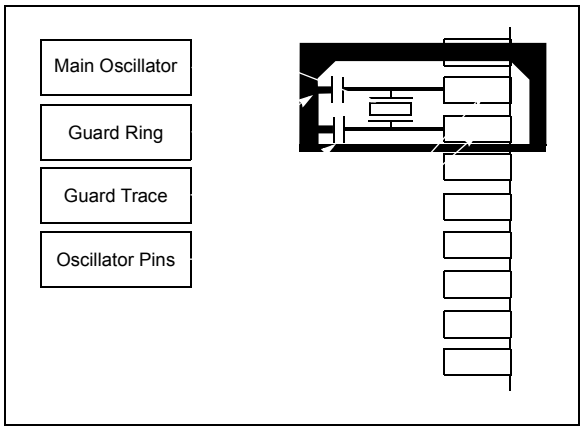
- *"Using MPLAB® ICD 3"* (poster) DS51765
- *"MPLAB® ICD 3 Design Advisory"* DS51764
- *"MPLAB® REAL ICE™ In-Circuit Emulator User's Guide"* DS51616
- *"Using MPLAB® REAL ICE™ In-Circuit Emulator"* (poster) DS51749

2.6 External Oscillator Pins

Many DSCs have options for at least two oscillators: a high-frequency Primary Oscillator and a low-frequency Secondary Oscillator. For details, see **Section 9.0 "Oscillator Configuration"** for details.

The oscillator circuit should be placed on the same side of the board as the device. Also, place the oscillator circuit close to the respective oscillator pins, not exceeding one-half inch (12 mm) distance between them. The load capacitors should be placed next to the oscillator itself, on the same side of the board. Use a grounded copper pour around the oscillator circuit to isolate them from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed. A suggested layout is shown in Figure 2-3.

FIGURE 2-3: SUGGESTED PLACEMENT OF THE OSCILLATOR CIRCUIT



3.0 CPU

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"CPU"** (DS70359) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X CPU has a 16-bit (data) modified Harvard architecture with an enhanced instruction set, including significant support for digital signal processing. The CPU has a 24-bit instruction word with a variable length opcode field. The Program Counter (PC) is 23 bits wide and addresses up to 4M x 24 bits of user program memory space.

An instruction prefetch mechanism helps maintain throughput and provides predictable execution. Most instructions execute in a single-cycle effective execution rate, with the exception of instructions that change the program flow, the double-word move (`MOV.D`) instruction, PSV accesses and the table instructions. Overhead-free program loop constructs are supported using the `DO` and `REPEAT` instructions, both of which are interruptible at any point.

3.1 Registers

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices have sixteen, 16-bit working registers in the programmer's model. Each of the working registers can act as a data, address or address offset register. The 16th working register (W15) operates as a Software Stack Pointer for interrupts and calls.

3.2 Instruction Set

The instruction set for dsPIC33EPXXXGP50X and dsPIC33EPXXXMC20X/50X devices has two classes of instructions: the MCU class of instructions and the DSP class of instructions. The instruction set for PIC24EPXXXGP/MC20X devices has the MCU class of instructions only and does not support DSP instructions. These two instruction classes are seamlessly integrated into the architecture and execute from a single execution unit. The instruction set includes many addressing modes and was designed for optimum C compiler efficiency.

3.3 Data Space Addressing

The base Data Space can be addressed as 64 Kbytes (32K words).

The Data Space includes two ranges of memory, referred to as X and Y data memory. Each memory range is accessible through its own independent Address Generation Unit (AGU). The MCU class of instructions operates solely through the X memory AGU, which accesses the entire memory map as one linear Data Space. On dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X devices, certain DSP instructions operate through the X and Y AGUs to support dual operand reads, which splits the data address space into two parts. The X and Y Data Spaces have memory locations that are device-specific, and are described further in the data memory maps in **Section 4.2 "Data Address Space"**.

The upper 32 Kbytes of the Data Space memory map can optionally be mapped into Program Space (PS) at any 32-Kbyte aligned program word boundary. The Program-to-Data Space mapping feature, known as Program Space Visibility (PSV), lets any instruction access Program Space as if it were Data Space. Moreover, the Base Data Space address is used in conjunction with a Read or Write Page register (DSRPAG or DSWPAG) to form an Extended Data Space (EDS) address. The EDS can be addressed as 8M words or 16 Mbytes. Refer to the **"Data Memory"** (DS70595) and **"Program Memory"** (DS70613) sections in the *"dsPIC33/PIC24 Family Reference Manual"* for more details on EDS, PSV and table accesses.

On the dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X devices, overhead-free circular buffers (Modulo Addressing) are supported in both X and Y address spaces. The Modulo Addressing removes the software boundary checking overhead for DSP algorithms. The X AGU Circular Addressing can be used with any of the MCU class of instructions. The X AGU also supports Bit-Reversed Addressing to greatly simplify input or output data re-ordering for radix-2 FFT algorithms. PIC24EPXXXGP/MC20X devices do not support Modulo and Bit-Reversed Addressing.

3.4 Addressing Modes

The CPU supports these addressing modes:

- Inherent (no operand)
- Relative
- Literal
- Memory Direct
- Register Direct
- Register Indirect

Each instruction is associated with a predefined addressing mode group, depending upon its functional requirements. As many as six addressing modes are supported for each instruction.

TABLE 4-37: PMD REGISTER MAP FOR PIC24EPXXXGP20X DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
PMD1	0760	T5MD	T4MD	T3MD	T2MD	T1MD	—	—	—	I2C1MD	U2MD	U1MD	SPI2MD	SPI1MD	—	—	AD1MD	0000
PMD2	0762	—	—	—	—	IC4MD	IC3MD	IC2MD	IC1MD	—	—	—	—	OC4MD	OC3MD	OC2MD	OC1MD	0000
PMD3	0764	—	—	—	—	—	CMPMD	—	—	CRCMD	—	—	—	—	—	I2C2MD	—	0000
PMD4	0766	—	—	—	—	—	—	—	—	—	—	—	—	REFOMD	CTMUMD	—	—	0000
PMD6	076A	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
PMD7	076C	—	—	—	—	—	—	—	—	—	—	—	DMA0MD DMA1MD DMA2MD DMA3MD	PTGMD	—	—	—	0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-38: PMD REGISTER MAP FOR PIC24EPXXXMC20X DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
PMD1	0760	T5MD	T4MD	T3MD	T2MD	T1MD	QEI1MD	PWMMD	—	I2C1MD	U2MD	U1MD	SPI2MD	SPI1MD	—	—	AD1MD	0000
PMD2	0762	—	—	—	—	IC4MD	IC3MD	IC2MD	IC1MD	—	—	—	—	OC4MD	OC3MD	OC2MD	OC1MD	0000
PMD3	0764	—	—	—	—	—	CMPMD	—	—	CRCMD	—	—	—	—	—	I2C2MD	—	0000
PMD4	0766	—	—	—	—	—	—	—	—	—	—	—	—	REFOMD	CTMUMD	—	—	0000
PMD6	076A	—	—	—	—	—	PWM3MD	PWM2MD	PWM1MD	—	—	—	—	—	—	—	—	0000
PMD7	076C	—	—	—	—	—	—	—	—	—	—	—	DMA0MD DMA1MD DMA2MD DMA3MD	PTGMD	—	—	—	0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

REGISTER 7-3: INTCON1: INTERRUPT CONTROL REGISTER 1

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
NSTDIS	OVAERR(1)	OVBERR(1)	COVAERR(1)	COVBERR(1)	OVATE(1)	OVBTE(1)	COVTE(1)
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0
SFTACERR(1)	DIV0ERR	DMACERR	MATHERR	ADDRERR	STKERR	OSCFAIL	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **NSTDIS:** Interrupt Nesting Disable bit
1 = Interrupt nesting is disabled
0 = Interrupt nesting is enabled

bit 14 **OVAERR:** Accumulator A Overflow Trap Flag bit(1)
1 = Trap was caused by overflow of Accumulator A
0 = Trap was not caused by overflow of Accumulator A

bit 13 **OVBERR:** Accumulator B Overflow Trap Flag bit(1)
1 = Trap was caused by overflow of Accumulator B
0 = Trap was not caused by overflow of Accumulator B

bit 12 **COVAERR:** Accumulator A Catastrophic Overflow Trap Flag bit(1)
1 = Trap was caused by catastrophic overflow of Accumulator A
0 = Trap was not caused by catastrophic overflow of Accumulator A

bit 11 **COVBERR:** Accumulator B Catastrophic Overflow Trap Flag bit(1)
1 = Trap was caused by catastrophic overflow of Accumulator B
0 = Trap was not caused by catastrophic overflow of Accumulator B

bit 10 **OVATE:** Accumulator A Overflow Trap Enable bit(1)
1 = Trap overflow of Accumulator A
0 = Trap is disabled

bit 9 **OVBTE:** Accumulator B Overflow Trap Enable bit(1)
1 = Trap overflow of Accumulator B
0 = Trap is disabled

bit 8 **COVTE:** Catastrophic Overflow Trap Enable bit(1)
1 = Trap on catastrophic overflow of Accumulator A or B is enabled
0 = Trap is disabled

bit 7 **SFTACERR:** Shift Accumulator Error Status bit(1)
1 = Math error trap was caused by an invalid accumulator shift
0 = Math error trap was not caused by an invalid accumulator shift

bit 6 **DIV0ERR:** Divide-by-Zero Error Status bit
1 = Math error trap was caused by a divide-by-zero
0 = Math error trap was not caused by a divide-by-zero

bit 5 **DMACERR:** DMAC Trap Flag bit
1 = DMAC trap has occurred
0 = DMAC trap has not occurred

Note 1: These bits are available on dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X devices only.

TABLE 11-2: INPUT PIN SELECTION FOR SELECTABLE INPUT SOURCES (CONTINUED)

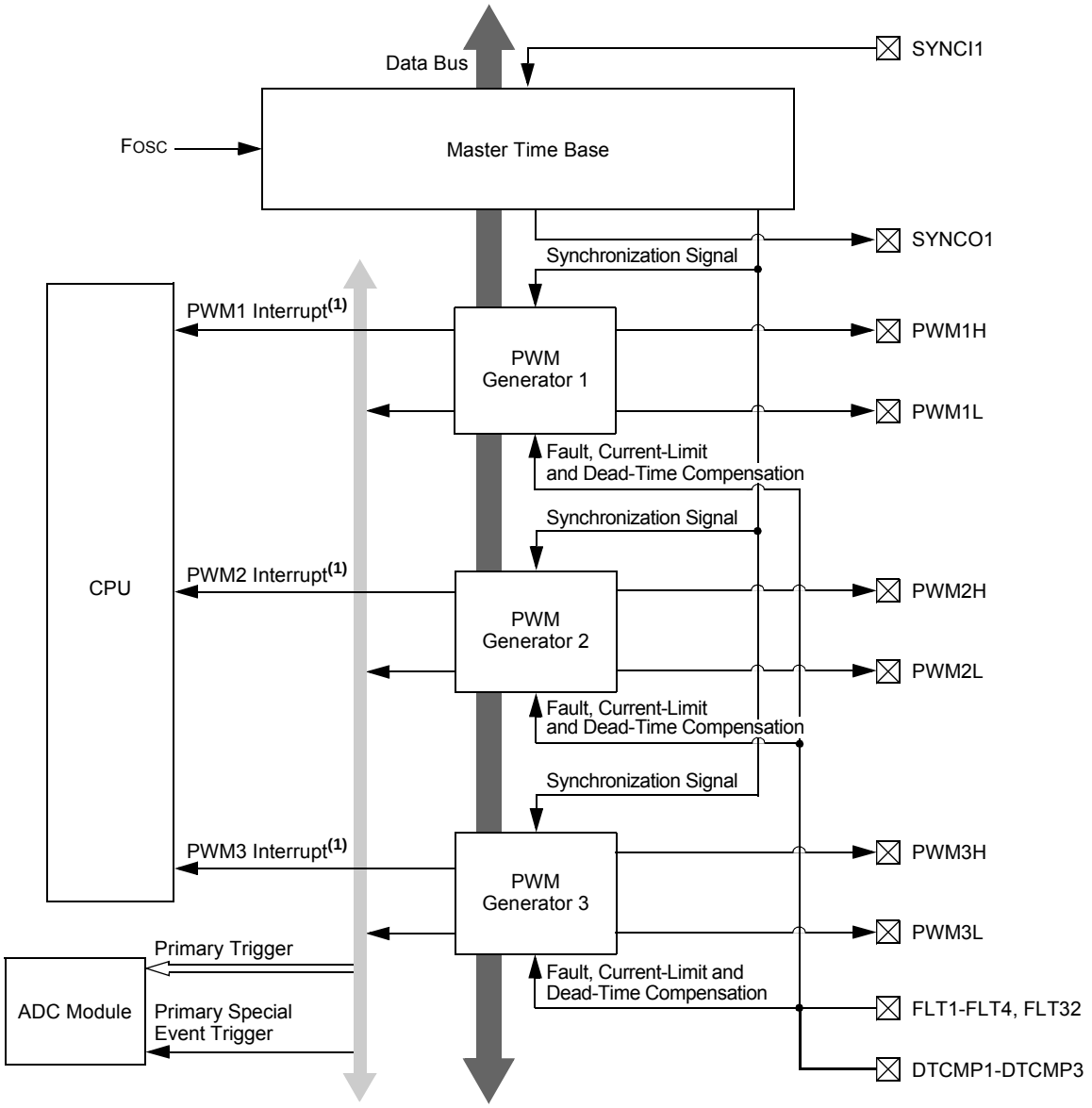
Peripheral Pin Select Input Register Value	Input/ Output	Pin Assignment	Peripheral Pin Select Input Register Value	Input/ Output	Pin Assignment
010 1000	I/O	RP40	101 0101	—	—
010 1001	I/O	RP41	101 0110	—	—
010 1010	I/O	RP42	101 0111	—	—
010 1011	I/O	RP43	101 1000	—	—
010 1100	I	RPI44	101 1001	—	—
101 1010	—	—	110 1101	—	—
101 1011	—	—	110 1110	—	—
101 1100	—	—	110 1111	—	—
101 1101	—	—	111 0000	—	—
101 1110	I	RPI94	111 0001	—	—
101 1111	I	RPI95	111 0010	—	—
110 0000	I	RPI96	111 0011	—	—
110 0001	I/O	RP97	111 0100	—	—
110 0010	—	—	111 0101	—	—
110 0011	—	—	111 0110	I/O	RP118
110 0100	—	—	111 0111	I	RPI119
110 0101	—	—	111 1000	I/O	RP120
110 0110	—	—	111 1001	I	RPI121
110 0111	—	—	111 1010	—	—
110 1000	—	—	111 1011	—	—
110 1001	—	—	111 1100	—	—
110 1010	—	—	111 1101	—	—
110 1011	—	—	111 1110	—	—
110 1100	—	—	111 1111	—	—

Legend: Shaded rows indicate PPS Input register values that are unimplemented.

Note 1: See **Section 11.4.4.1 “Virtual Connections”** for more information on selecting this pin assignment.

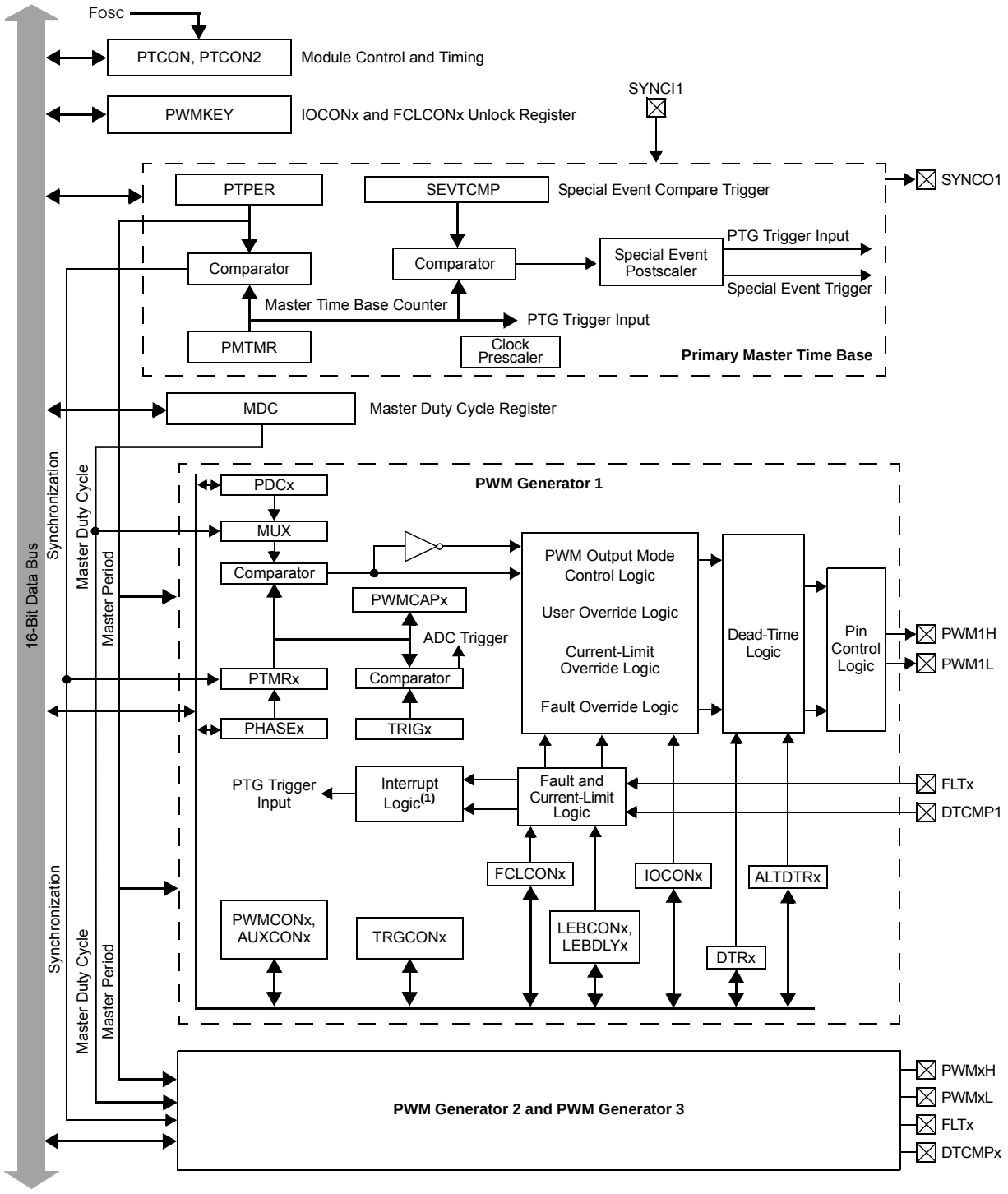
2: These inputs are available on dsPIC33EPXXXGP/MC50X devices only.

FIGURE 16-1: HIGH-SPEED PWMx MODULE ARCHITECTURAL OVERVIEW



Note 1: The PWM interrupts are generated by logically ORing the FLTSTAT, CLSTAT and TRGSTAT status bits for the given PWM generator. Refer to the "*dsPIC33/PIC24 Family Reference Manual*", **"High-Speed PWM"** (DS70645) for more information.

FIGURE 16-2: HIGH-SPEED PWMx MODULE REGISTER INTERCONNECTION DIAGRAM



Note 1: The PWM interrupts are generated by logically ORing the FLTSTAT, CLSTAT and TRGSTAT status bits for the given PWM generator. Refer to the "*dsPIC33/PIC24 Family Reference Manual*", **"High-Speed PWM"** (DS70645) for more information.

REGISTER 16-13: IOCONx: PWMx I/O CONTROL REGISTER(2)

R/W-1	R/W-1	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PENH	PENL	POLH	POLL	PMOD1(1)	PMOD0(1)	OVRENH	OVRENL
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
OVRDAT1	OVRDAT0	FLTDAT1	FLTDAT0	CLDAT1	CLDAT0	SWAP	OSYNC
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **PENH:** PWMxH Output Pin Ownership bit
1 = PWMx module controls PWMxH pin
0 = GPIO module controls PWMxH pin

bit 14 **PENL:** PWMxL Output Pin Ownership bit
1 = PWMx module controls PWMxL pin
0 = GPIO module controls PWMxL pin

bit 13 **POLH:** PWMxH Output Pin Polarity bit
1 = PWMxH pin is active-low
0 = PWMxH pin is active-high

bit 12 **POLL:** PWMxL Output Pin Polarity bit
1 = PWMxL pin is active-low
0 = PWMxL pin is active-high

bit 11-10 **PMOD<1:0>:** PWMx # I/O Pin Mode bits(1)
11 = Reserved; do not use
10 = PWMx I/O pin pair is in the Push-Pull Output mode
01 = PWMx I/O pin pair is in the Redundant Output mode
00 = PWMx I/O pin pair is in the Complementary Output mode

bit 9 **OVRENH:** Override Enable for PWMxH Pin bit
1 = OVRDAT<1> controls output on PWMxH pin
0 = PWMx generator controls PWMxH pin

bit 8 **OVRENL:** Override Enable for PWMxL Pin bit
1 = OVRDAT<0> controls output on PWMxL pin
0 = PWMx generator controls PWMxL pin

bit 7-6 **OVRDAT<1:0>:** Data for PWMxH, PWMxL Pins if Override is Enabled bits
If OVERENH = 1, PWMxH is driven to the state specified by OVRDAT<1>.
If OVERENL = 1, PWMxL is driven to the state specified by OVRDAT<0>.

bit 5-4 **FLTDAT<1:0>:** Data for PWMxH and PWMxL Pins if FLTMOD is Enabled bits
If Fault is active, PWMxH is driven to the state specified by FLTDAT<1>.
If Fault is active, PWMxL is driven to the state specified by FLTDAT<0>.

bit 3-2 **CLDAT<1:0>:** Data for PWMxH and PWMxL Pins if CLMOD is Enabled bits
If current-limit is active, PWMxH is driven to the state specified by CLDAT<1>.
If current-limit is active, PWMxL is driven to the state specified by CLDAT<0>.

Note 1: These bits should not be changed after the PWMx module is enabled (PTEN = 1).
2: If the PWMLOCK Configuration bit (FOSCSEL<6>) is a '1', the IOCONx register can only be written after the unlock sequence has been executed.

TABLE 24-2: PTG OUTPUT DESCRIPTIONS

PTG Output Number	PTG Output Description
PTGO0	Trigger/Synchronization Source for OC1
PTGO1	Trigger/Synchronization Source for OC2
PTGO2	Trigger/Synchronization Source for OC3
PTGO3	Trigger/Synchronization Source for OC4
PTGO4	Clock Source for OC1
PTGO5	Clock Source for OC2
PTGO6	Clock Source for OC3
PTGO7	Clock Source for OC4
PTGO8	Trigger/Synchronization Source for IC1
PTGO9	Trigger/Synchronization Source for IC2
PTGO10	Trigger/Synchronization Source for IC3
PTGO11	Trigger/Synchronization Source for IC4
PTGO12	Sample Trigger for ADC
PTGO13	Sample Trigger for ADC
PTGO14	Sample Trigger for ADC
PTGO15	Sample Trigger for ADC
PTGO16	PWM Time Base Synchronous Source for PWM(1)
PTGO17	PWM Time Base Synchronous Source for PWM(1)
PTGO18	Mask Input Select for Op Amp/Comparator
PTGO19	Mask Input Select for Op Amp/Comparator
PTGO20	Reserved
PTGO21	Reserved
PTGO22	Reserved
PTGO23	Reserved
PTGO24	Reserved
PTGO25	Reserved
PTGO26	Reserved
PTGO27	Reserved
PTGO28	Reserved
PTGO29	Reserved
PTGO30	PTG Output to PPS Input Selection
PTGO31	PTG Output to PPS Input Selection

Note 1: This feature is only available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices.

25.1.2 OP AMP CONFIGURATION B

Figure 25-7 shows a typical inverting amplifier circuit with the output of the op amp (OAxOUT) externally routed to a separate analog input pin (ANy) on the device. This op amp configuration is slightly different in terms of the op amp output and the ADC input connection, therefore, RINT1 is not included in the transfer function. However, this configuration requires the designer to externally route the op amp output (OAxOUT) to another analog input pin (ANy). See Table 30-53 in **Section 30.0 "Electrical Characteristics"** for the typical value of RINT1. Table 30-60 and Table 30-61 in **Section 30.0 "Electrical Characteristics"** describe the minimum sample time (TSAMP) requirements for the ADC module in this configuration.

Figure 25-7 also defines the equation to be used to calculate the expected voltage at point VOAxOUT. This is the typical inverting amplifier equation.

25.2 Op Amp/Comparator Resources

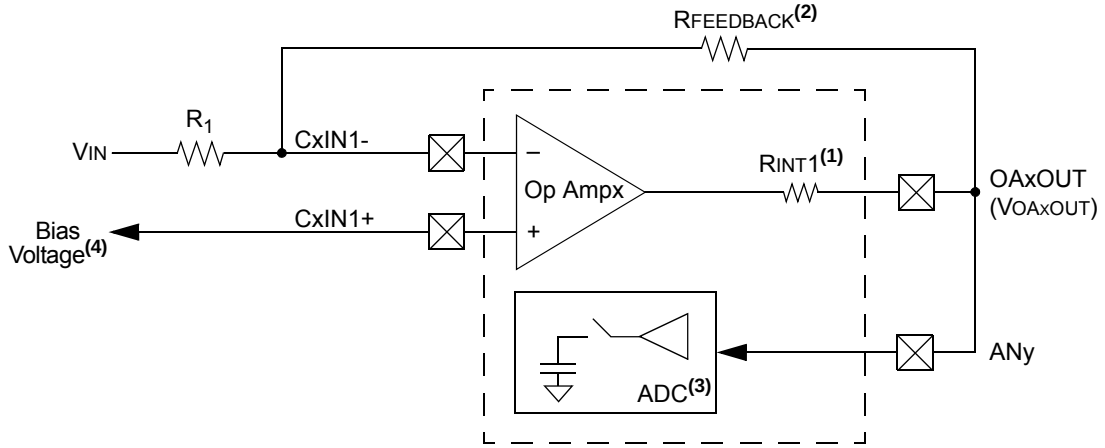
Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464

25.2.1 KEY RESOURCES

- **"Op Amp/Comparator"** (DS70357) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

FIGURE 25-7: OP AMP CONFIGURATION B



$$V_{OAxOUT} = \left(\frac{R_{FEEDBACK}}{R_1}\right)(\ Bias\ Voltage - V_{IN} \ )$$

Note 1: See Table 30-53 for the Typical value.
2: See Table 30-53 for the Minimum value for the feedback resistor.
3: See Table 30-60 and Table 30-61 for the minimum sample time (TSAMP).
4: CVREF1O or CVREF2O are two options that are available for supplying bias voltage to the op amps.

REGISTER 25-2: CMxCON: COMPARATOR x CONTROL REGISTER (x = 1, 2 OR 3)

R/W-0	R/W-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0
CON	COE(2)	CPOL	—	—	OPMODE	CEVT	COUT
bit 15							bit 8

R/W-0	R/W-0	U-0	R/W-0	U-0	U-0	R/W-0	R/W-0
EVPOL1	EVPOL0	—	CREF(1)	—	—	CCH1(1)	CCH0(1)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **CON:** Op Amp/Comparator Enable bit
1 = Op amp/comparator is enabled
0 = Op amp/comparator is disabled

bit 14 **COE:** Comparator Output Enable bit(2)
1 = Comparator output is present on the CxOUT pin
0 = Comparator output is internal only

bit 13 **CPOL:** Comparator Output Polarity Select bit
1 = Comparator output is inverted
0 = Comparator output is not inverted

bit 12-11 **Unimplemented:** Read as '0'

bit 10 **OPMODE:** Op Amp/Comparator Operation Mode Select bit
1 = Circuit operates as an op amp
0 = Circuit operates as a comparator

bit 9 **CEVT:** Comparator Event bit
1 = Comparator event according to the EVPOL<1:0> settings occurred; disables future triggers and interrupts until the bit is cleared
0 = Comparator event did not occur

bit 8 **COUT:** Comparator Output bit
When CPOL = 0 (non-inverted polarity):
1 = $V_{IN+} > V_{IN-}$
0 = $V_{IN+} < V_{IN-}$
When CPOL = 1 (inverted polarity):
1 = $V_{IN+} < V_{IN-}$
0 = $V_{IN+} > V_{IN-}$

Note 1: Inputs that are selected and not available will be tied to V_{SS}. See the **"Pin Diagrams"** section for available inputs for each package.

2: This output is not available when OPMODE (CMxCON<10>) = 1.

TABLE 28-2: INSTRUCTION SET OVERVIEW

Base Instr #	Assembly Mnemonic	Assembly Syntax		Description	# of Words	# of Cycles(2)	Status Flags Affected
1	ADD	ADD	Acc(1)	Add Accumulators	1	1	OA,OB,SA,SB
		ADD	f	f = f + WREG	1	1	C,DC,N,OV,Z
		ADD	f,WREG	WREG = f + WREG	1	1	C,DC,N,OV,Z
		ADD	#lit10,Wn	Wd = lit10 + Wd	1	1	C,DC,N,OV,Z
		ADD	Wb,Ws,Wd	Wd = Wb + Ws	1	1	C,DC,N,OV,Z
		ADD	Wb,#lit5,Wd	Wd = Wb + lit5	1	1	C,DC,N,OV,Z
		ADD	Wso,#Slit4,Acc	16-bit Signed Add to Accumulator	1	1	OA,OB,SA,SB
2	ADDC	ADDC	f	f = f + WREG + (C)	1	1	C,DC,N,OV,Z
		ADDC	f,WREG	WREG = f + WREG + (C)	1	1	C,DC,N,OV,Z
		ADDC	#lit10,Wn	Wd = lit10 + Wd + (C)	1	1	C,DC,N,OV,Z
		ADDC	Wb,Ws,Wd	Wd = Wb + Ws + (C)	1	1	C,DC,N,OV,Z
		ADDC	Wb,#lit5,Wd	Wd = Wb + lit5 + (C)	1	1	C,DC,N,OV,Z
3	AND	AND	f	f = f .AND. WREG	1	1	N,Z
		AND	f,WREG	WREG = f .AND. WREG	1	1	N,Z
		AND	#lit10,Wn	Wd = lit10 .AND. Wd	1	1	N,Z
		AND	Wb,Ws,Wd	Wd = Wb .AND. Ws	1	1	N,Z
		AND	Wb,#lit5,Wd	Wd = Wb .AND. lit5	1	1	N,Z
4	ASR	ASR	f	f = Arithmetic Right Shift f	1	1	C,N,OV,Z
		ASR	f,WREG	WREG = Arithmetic Right Shift f	1	1	C,N,OV,Z
		ASR	Ws,Wd	Wd = Arithmetic Right Shift Ws	1	1	C,N,OV,Z
		ASR	Wb,Wns,Wnd	Wnd = Arithmetic Right Shift Wb by Wns	1	1	N,Z
		ASR	Wb,#lit5,Wnd	Wnd = Arithmetic Right Shift Wb by lit5	1	1	N,Z
5	BCLR	BCLR	f,#bit4	Bit Clear f	1	1	None
		BCLR	Ws,#bit4	Bit Clear Ws	1	1	None
6	BRA	BRA	C,Expr	Branch if Carry	1	1 (4)	None
		BRA	GE,Expr	Branch if greater than or equal	1	1 (4)	None
		BRA	GEU,Expr	Branch if unsigned greater than or equal	1	1 (4)	None
		BRA	GT,Expr	Branch if greater than	1	1 (4)	None
		BRA	GTU,Expr	Branch if unsigned greater than	1	1 (4)	None
		BRA	LE,Expr	Branch if less than or equal	1	1 (4)	None
		BRA	LEU,Expr	Branch if unsigned less than or equal	1	1 (4)	None
		BRA	LT,Expr	Branch if less than	1	1 (4)	None
		BRA	LTU,Expr	Branch if unsigned less than	1	1 (4)	None
		BRA	N,Expr	Branch if Negative	1	1 (4)	None
		BRA	NC,Expr	Branch if Not Carry	1	1 (4)	None
		BRA	NN,Expr	Branch if Not Negative	1	1 (4)	None
		BRA	NOV,Expr	Branch if Not Overflow	1	1 (4)	None
		BRA	NZ,Expr	Branch if Not Zero	1	1 (4)	None
		BRA	OA,Expr(1)	Branch if Accumulator A overflow	1	1 (4)	None
		BRA	OB,Expr(1)	Branch if Accumulator B overflow	1	1 (4)	None
		BRA	OV,Expr(1)	Branch if Overflow	1	1 (4)	None
		BRA	SA,Expr(1)	Branch if Accumulator A saturated	1	1 (4)	None
		BRA	SB,Expr(1)	Branch if Accumulator B saturated	1	1 (4)	None
		BRA	Expr	Branch Unconditionally	1	4	None
		BRA	Z,Expr	Branch if Zero	1	1 (4)	None
		BRA	Wn	Computed Branch	1	4	None
7	BSET	BSET	f,#bit4	Bit Set f	1	1	None
		BSET	Ws,#bit4	Bit Set Ws	1	1	None
8	BSW	BSW.C	Ws,Wb	Write C bit to Ws<Wb>	1	1	None
		BSW.Z	Ws,Wb	Write Z bit to Ws<Wb>	1	1	None

Note 1: These instructions are available in dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.

2: Read and Read-Modify-Write (e.g., bit operations and logical operations) on non-CPU SFRs incur an additional instruction cycle.

TABLE 30-6: DC CHARACTERISTICS: OPERATING CURRENT (IDD)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Parameter No.	**Typ.**	**Max.**	**Units**	**Conditions**		
Operating Current (IDD)(1)						
DC20d	9	15	mA	-40°C	3.3V	10 MIPS
DC20a	9	15	mA	+25°C		
DC20b	9	15	mA	+85°C		
DC20c	9	15	mA	+125°C		
DC22d	16	25	mA	-40°C	3.3V	20 MIPS
DC22a	16	25	mA	+25°C		
DC22b	16	25	mA	+85°C		
DC22c	16	25	mA	+125°C		
DC24d	27	40	mA	-40°C	3.3V	40 MIPS
DC24a	27	40	mA	+25°C		
DC24b	27	40	mA	+85°C		
DC24c	27	40	mA	+125°C		
DC25d	36	55	mA	-40°C	3.3V	60 MIPS
DC25a	36	55	mA	+25°C		
DC25b	36	55	mA	+85°C		
DC25c	36	55	mA	+125°C		
DC26d	41	60	mA	-40°C	3.3V	70 MIPS
DC26a	41	60	mA	+25°C		
DC26b	41	60	mA	+85°C		

Note 1: IDD is primarily a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption. The test conditions for all IDD measurements are as follows:

- Oscillator is configured in EC mode with PLL, OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration Word
- All I/O pins are configured as inputs and pulled to VSS
- $\overline{MCLR}$ = VDD, WDT and FSCM are disabled
- CPU, SRAM, program memory and data memory are operational
- No peripheral modules are operating; however, every peripheral is being clocked (all PMDx bits are zeroed)
- CPU is executing `while(1){NOP();}` statement
- JTAG is disabled

FIGURE 30-13: QEI MODULE INDEX PULSE TIMING CHARACTERISTICS (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X DEVICES ONLY)

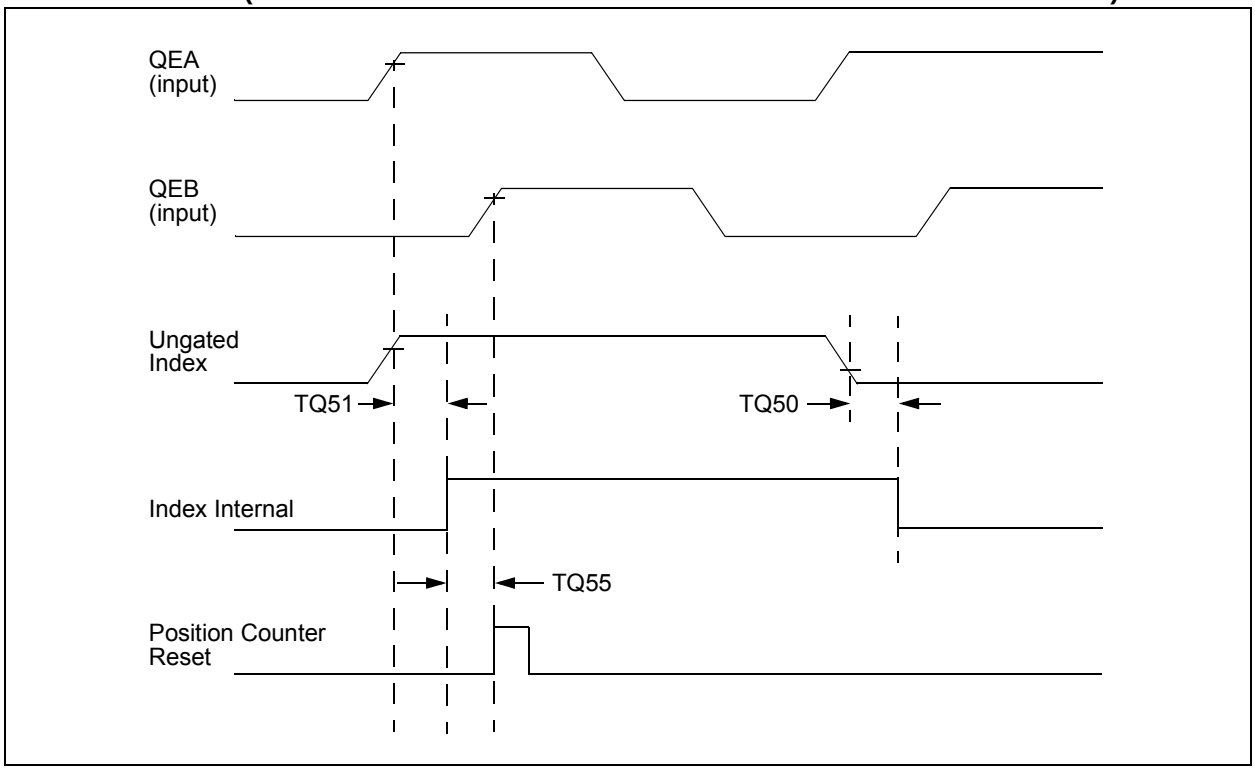


TABLE 30-32: QEI INDEX PULSE TIMING REQUIREMENTS (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X DEVICES ONLY)

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Param No.	**Symbol**	**Characteristic(1)**	**Min.**	**Max.**	**Units**	**Conditions**
TQ50	TqiL	Filter Time to Recognize Low, with Digital Filter	3 * N * TCY	—	ns	N = 1, 2, 4, 16, 32, 64, 128 and 256 **(Note 2)**
TQ51	TqiH	Filter Time to Recognize High, with Digital Filter	3 * N * TCY	—	ns	N = 1, 2, 4, 16, 32, 64, 128 and 256 **(Note 2)**
TQ55	Tqidxr	Index Pulse Recognized to Position Counter Reset (ungated index)	3 TCY	—	ns	

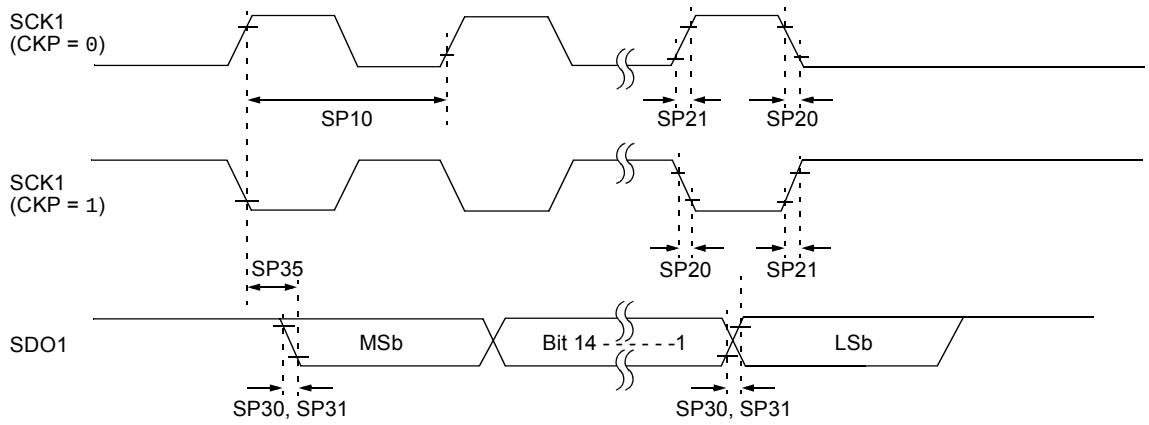
Note 1: These parameters are characterized but not tested in manufacturing.

2: Alignment of index pulses to QEA and QEB is shown for position counter Reset timing only. Shown for forward direction only (QEA leads QEB). Same timing applies for reverse direction (QEA lags QEB) but index pulse recognition occurs on the falling edge.

TABLE 30-41: SPI1 MAXIMUM DATA/CLOCK RATE SUMMARY

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Maximum Data Rate	**Master Transmit Only (Half-Duplex)**	**Master Transmit/Receive (Full-Duplex)**	**Slave Transmit/Receive (Full-Duplex)**	**CKE**	**CKP**	**SMP**
15 MHz	Table 30-42	—	—	0,1	0,1	0,1
10 MHz	—	Table 30-43	—	1	0,1	1
10 MHz	—	Table 30-44	—	0	0,1	1
15 MHz	—	—	Table 30-45	1	0	0
11 MHz	—	—	Table 30-46	1	1	0
15 MHz	—	—	Table 30-47	0	1	0
11 MHz	—	—	Table 30-48	0	0	0

FIGURE 30-22: SPI1 MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY, CKE = 0) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-53: OP AMP/COMPARATOR SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)(1) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
Comparator AC Characteristics							
CM10	TRESP	Response Time(3)	—	19	—	ns	V+ input step of 100 mV, V- input held at VDD/2
CM11	TMC2OV	Comparator Mode Change to Output Valid	—	—	10	µs	
Comparator DC Characteristics							
CM30	VOFFSET	Comparator Offset Voltage	—	±10	40	mV	
CM31	VHYST	Input Hysteresis Voltage(3)	—	30	—	mV	
CM32	TRISE/ TFALL	Comparator Output Rise/ Fall Time(3)	—	20	—	ns	1 pF load capacitance on input
CM33	VGAIN	Open-Loop Voltage Gain(3)	—	90	—	db	
CM34	VICM	Input Common-Mode Voltage	AVSS	—	AVDD	V	
Op Amp AC Characteristics							
CM20	SR	Slew Rate(3)	—	9	—	V/µs	10 pF load
CM21a	PM	Phase Margin (Configuration A)(3,4)	—	55	—	Degree	G = 100V/V; 10 pF load
CM21b	PM	Phase Margin (Configuration B)(3,5)	—	40	—	Degree	G = 100V/V; 10 pF load
CM22	GM	Gain Margin(3)	—	20	—	db	G = 100V/V; 10 pF load
CM23a	GBW	Gain Bandwidth (Configuration A)(3,4)	—	10	—	MHz	10 pF load
CM23b	GBW	Gain Bandwidth (Configuration B)(3,5)	—	6	—	MHz	10 pF load

Note 1: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance. Refer to Parameter BO10 in Table 30-13 for the minimum and maximum BOR values.

2: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated.

3: Parameter is characterized but not tested in manufacturing.

4: See Figure 25-6 for configuration information.

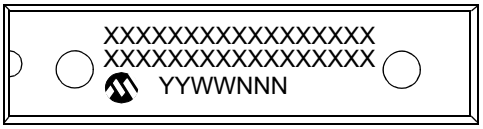
5: See Figure 25-7 for configuration information.

6: Resistances can vary by ±10% between op amps.

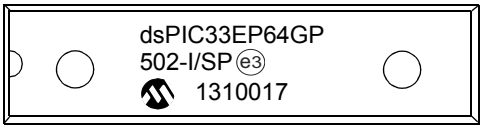
33.0 PACKAGING INFORMATION

33.1 Package Marking Information

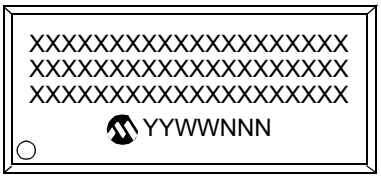
28-Lead SPDIP



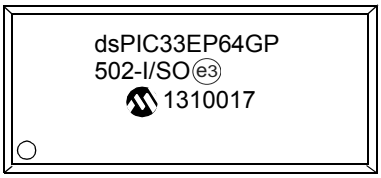
Example



28-Lead SOIC (.300”)



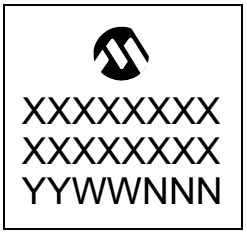
Example



28-Lead SSOP

Example

28-Lead QFN-S (6x6x0.9 mm)



Example

Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code
	e3	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.